



**25<sup>th</sup> International Conference on Electronic Packaging Technology**

**August 07 to 09, 2024, Tianjin, China**

**<http://www.icept.org>**

**Speech subject:** **Entransy and Electronics Packaging Thermal Management**

**Speech leader:** Zeng Yuan Guo, Academician of the Chinese Academy of Sciences, Professor, Department of Engineering Mechanics, Tsinghua University

**Speech Description/Objective:**

**Speech Outline:**

**Who Should Attend:**

**Introduction of Speaker:**

Zeng Yuan Guo, born on February 28, 1936 in Wuxi, Jiangsu, is an engineering thermophysicist, an academician of the Chinese Academy of Sciences, and a professor and doctoral supervisor of the Department of Engineering Mechanics of Tsinghua University.

He graduated from the Department of Power Machinery, Tsinghua University in 1959. In 1979, he went to work as a Humboldt scholar at the Technische Universität München, Germany; In 1997, he was elected as an academician of the Chinese Academy of Sciences. In 1999, he served as the dean of the School of Mechanical Engineering of Tsinghua University. In 2005, he won the Lifetime Achievement Award for Microscale Heat Transfer from the American Society of Mechanical Engineers, ASME; On March 29, 2017, he received the Asian Thermal Science Outstanding Achievement Award from the Asian Federation of Thermal Science and Engineering.

The research of super-additive element is mainly thermal science and technology research, involving thermal fluids, hot plasma, flow and heat transfer under microgravity conditions, microscale heat transfer and heat transfer intensification.